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Dept	B3(cs)
Semester	4th
Assignment No	5

Give detail answer to each of the following.

a) Discuss different types of Semiconductor memories in detail.

Ans There are various types of Semiconductor memories - The most common is referred to as RAM (Random access memory). Most types have the property of RANDOM ACCESS MEMORY, which means that it takes the same amount of time to access any memory location.

Here is a table of Semiconductor Memory types.

Memory type	Category	Erase	write mechanism	volatility
RAM (random memory)	Read/write memory	Electrically, Bit level	Electrically	volatile
ROM	Read-only memory	Not Possible	Masks	Non volatile
PROM		UV-light, chip level		
EPROM	Read mostly memory	Electrically, byte level		Non volatile
EEROM		Electrically, block level	Electrically	
Flash memory				

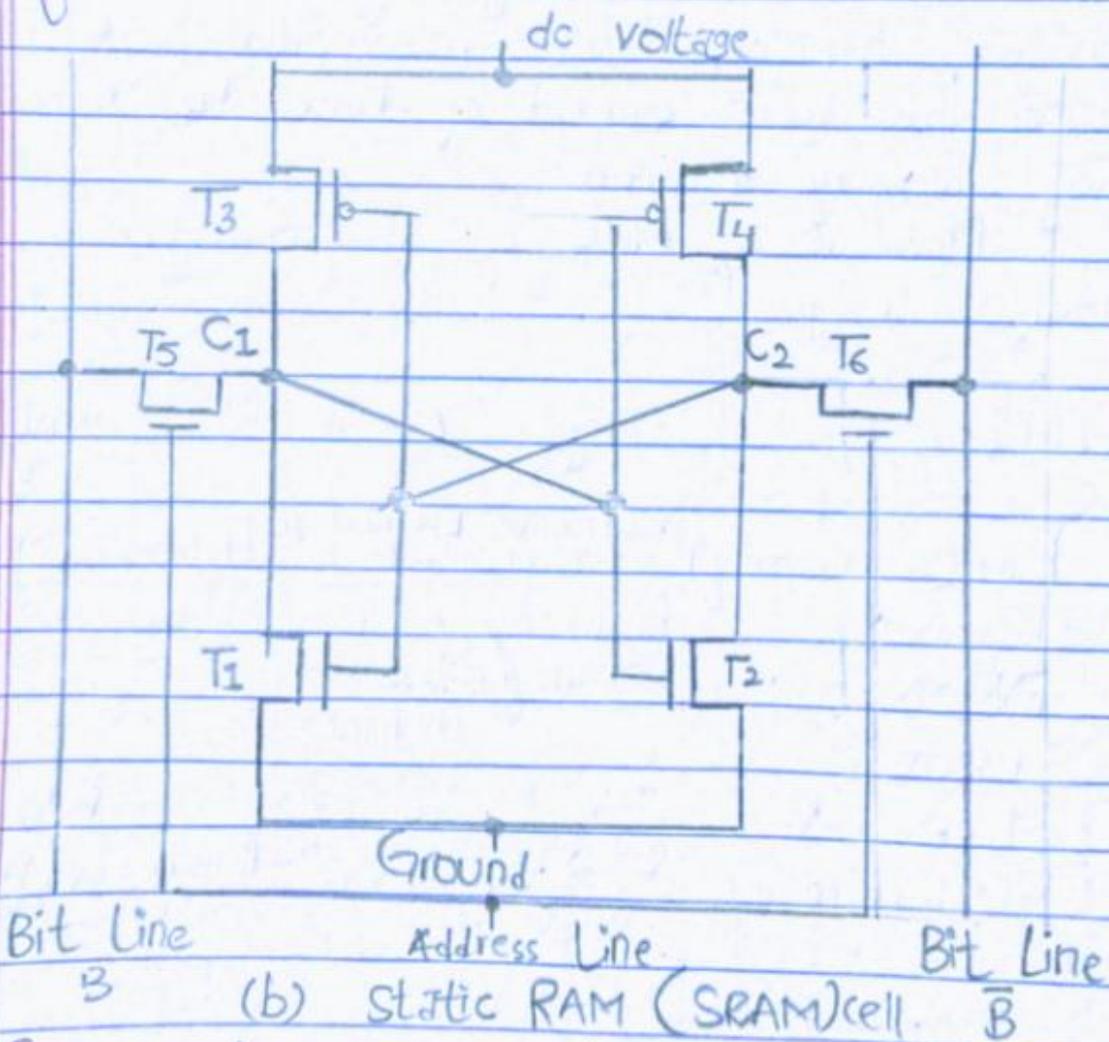
b) Explain the read and write operation for the SRAM cell using diagram.

Ans. Read operation:-

In SRAM, for any operation to be performed, the word line should be high. To perform read operation, initially---

→ Write operation:-

Consider the memory bits consists of $Q = 0$ and $Q' = 1$.



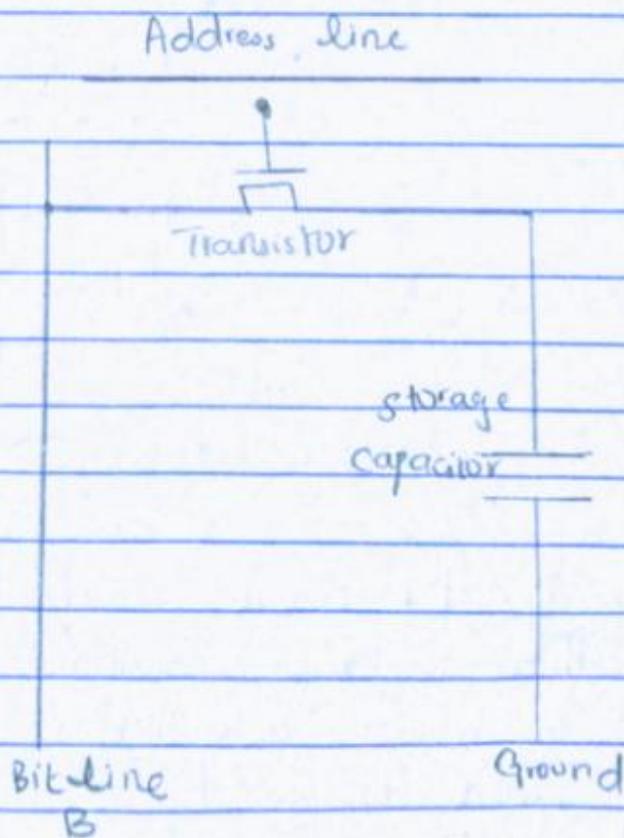
c) Explain the read and write operation for the DRAM cell using diagram.

Ans) Read operation:-

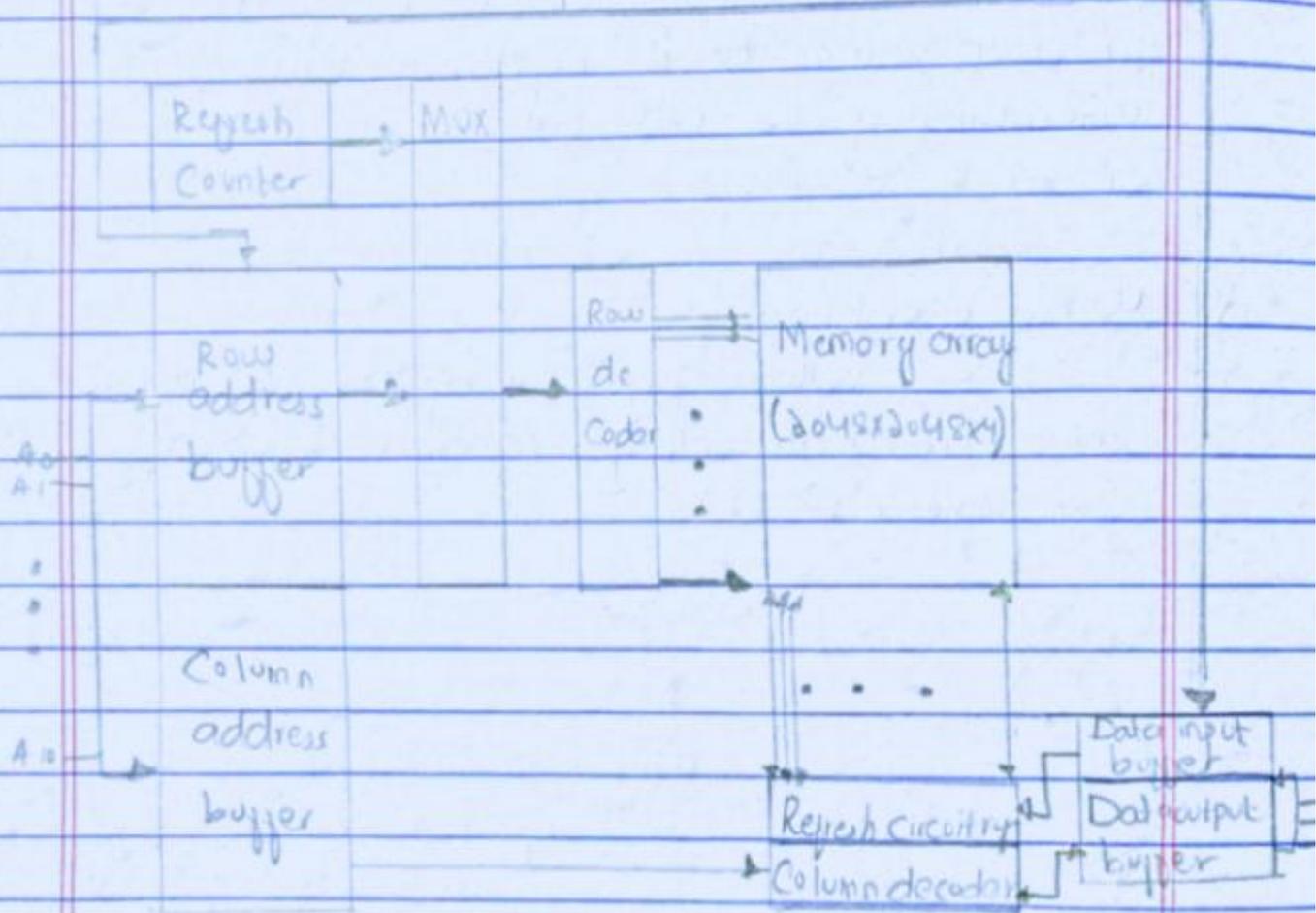
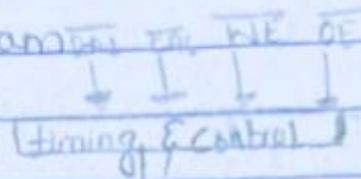
When the address line is selected, the transistor turns on and the charge stored on the capacitor is fed out onto a bit line & to a sense line amplifier. It compares the capacitor voltage to a reference value V_{ref} & determines if the cell contains a logic 1 or a logic 0.

Write operation:-

A voltage signal is applied to a bit line:- a high voltage represents 1 & a low represents 0.



d) Discuss 16-Mbit DRAM (4Mx4) organization using diagram



Typical 16-Mbit DRAM (4Mx4)

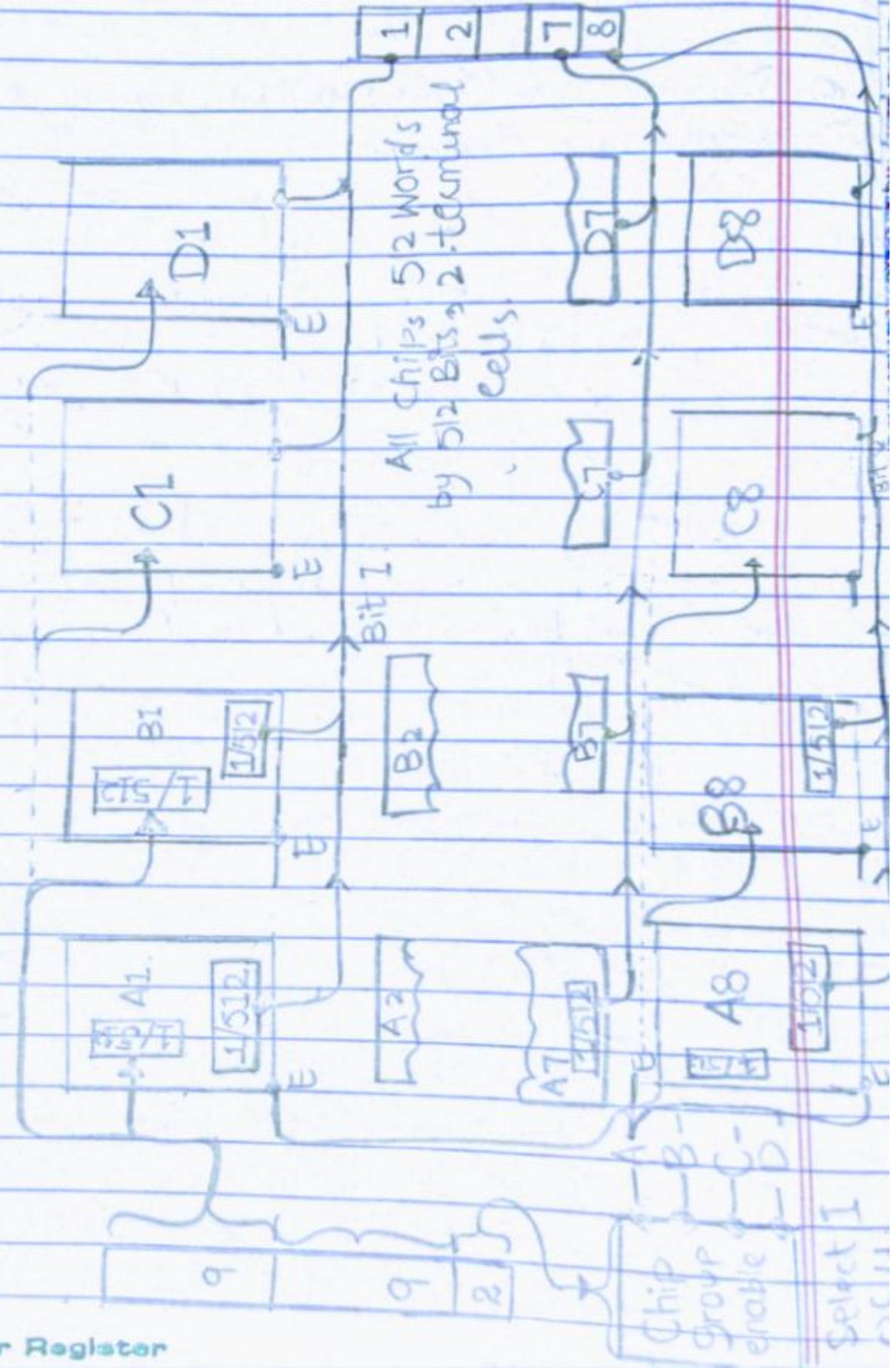
Because only 4 bits are read/written to this DRAM, there must be multiple DRAMs connected to the memory controller to read/write a word of data to the bus.

All the DRAMs require a refresh operation. A simple technique for refreshing is, in effect, to disable the DRAM

chip while all data cells are refreshed.
The refresh counter steps through all of the row values. This causes each cell in row to be refreshed.

e) Discuss 1MB (256K x 4 x 8Bit) memory organization using diagram.

(6)



SEC-DED for each 32 bits of memory, for a 22% overhead.

g) How is syndrome for the Hamming Code interpreted?

Ans Syndrome for the Hamming Code interpreted as follows.

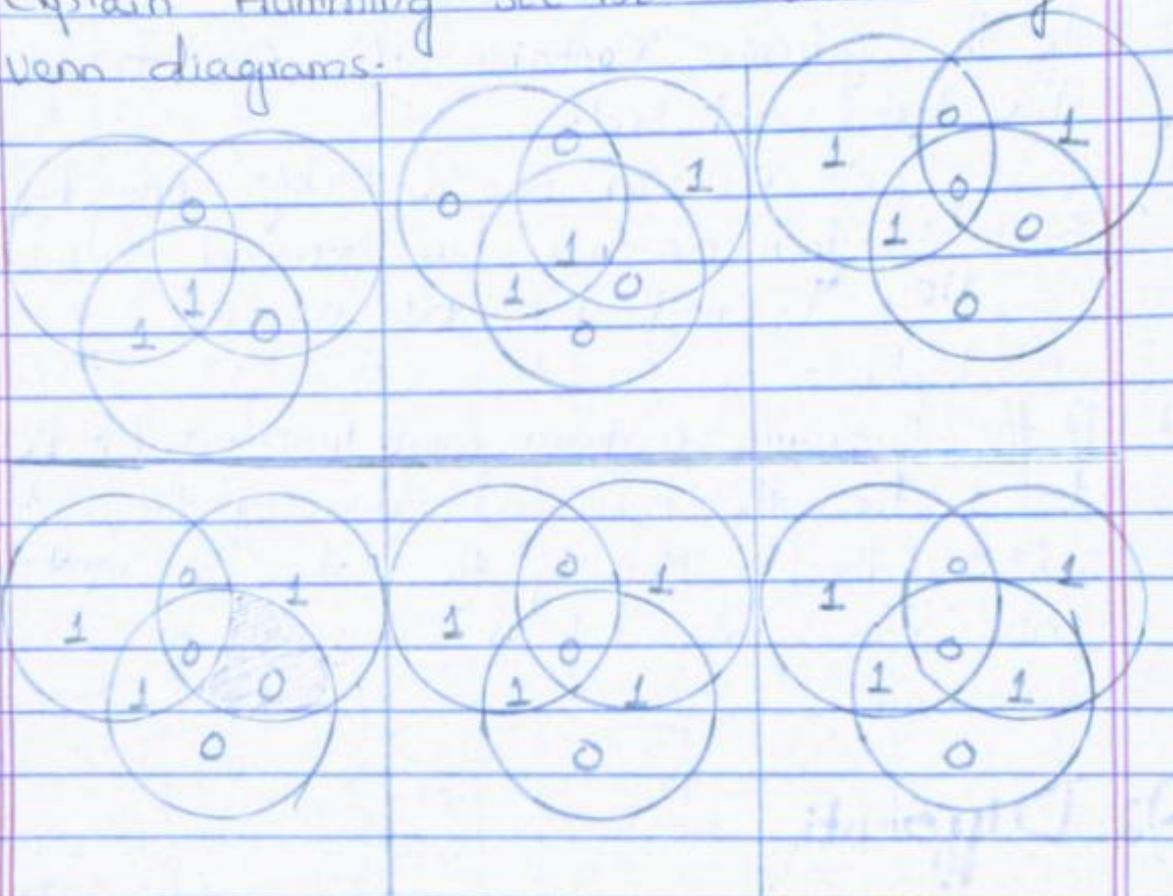
+ If the syndrome contains all 0s, no error has been detected.

+ If syndrome contains one and only one bit set to 1, then an error has occurred in one of the 4 check bits. No correction is needed.

+ If the syndrome contains more than one bit set to 1, then the numerical value of the syndrome indicates the position of the data bit in error. This data bit is inverted for correction.

The possible organization is required of a memory consisting of $1M$ word by 8 bits per word. In this case we have four columns of chips, each column containing 256k words arranged.

f) Explain Hamming SEC-DEC code using Venn diagrams.



Hamming SEC-DEC code

With 1 bit-per-chip organization, an SEC-DEC code is generally considered adequate. e.g. the IBM 30xx implementations used an 8-bit SEC-DEC code for each 64 bits of data in main memory. The size of main memory is actually about 12% larger than is apparent to the user. The VAX computers used a 7-bit

Q2 Differentiate each of the following.

a) DRAM and SRAM.

	DRAM	SRAM
+	DRAM is more dense and less expensive.	SRAM is expensive.
+	DRAM requires the supporting refresh circuitry.	SRAM does not require any refresh circuitry.
+	DRAM are normal in speed.	SRAM are faster in speed than DRAM.
+	SRAM is used for cache memory.	DRAM is used for main memory.

b) EEPROM and flash memory.

	EEPROM	Flash memory
+	EEPROM devices can erase any byte of memory at any time.	Flash memory can only erase an entire chunk, or "Sector" of memory at a time.
+	EEPROM uses NOR type memory.	Flash memory uses NAND type memory.
+	EEPROM is byte-wise erasable.	Flash is block-wise erasable.

c) Hard failure and Soft error in Semiconductor memories.

Ans A hard failure is a permanent physical defect so that the memory cell or cells affected cannot reliably store data but become stuck at 0 or 1 or switch erratically b/w 0 and 1. Hard errors can be caused by harsh environmental abuse, manufacturing defects, and wear.

where as

Soft error is a random, nondestructive event that alters the contents of one or more memory cells without damaging the memory. Soft errors can be caused by power supply problems or alpha particles.

Q3 Suppose an 8-bit data word stored in memory is 10101010. Using the Hamming algorithm, determine what check bits would be stored in memory with the data word. Show how you get answer.

Ans

$$M = 8$$

$$2^k - 1 \geq k + m$$

$$2^4 - 1 \geq 4 + 8$$

$$15 \geq 12.$$

1	2	3	4	5	6	7	8	9	10	11	12
1	0	1	1	1	0	0	1	0	0	1	0

The check bits are in a bit numbers 1, 2, 4 & 8.

- Check bit 8 calculated by values in bit numbers: 9, 10, 11 and 12.
- Check bit 4 calculated by values in bit numbers: 5, 6, 7 and 12.
- Check bit 2 calculated by values in bit numbers: 3, 6, 7, 10 and 11.
- Check bit 1 calculated by values in Bit numbers: 3, 5, 7, 9, 10 and 11.

Thus, the check bits are: 1011.